CLAIMS

[Claim 1]

An epoxy resin composition comprising a tetramethylbiphenol type epoxy resin, a phosphorus-based curing accelerator, and a curing agent, the tetramethylbiphenol type epoxy resin having a content of a sodium ion of 2 to 12ppm and the epoxy resin composition having a content of a sodium ion of 1.2 to 7.6ppm which is determined by the following measurement method, wherein a content of the phosphorus-based curing accelerator is 73 or more and 439 or less in a P/Na molar ratio, which is calculated as a phosphorus atom, to a sodium ion which is in the epoxy resin composition and determined by the following measurement method:

(Measurement Method) Measurement by the atomic absorption spectrometry using a solution wherein a sample is dissolved in N-methylpyrrolidone

[Claim 2]

The epoxy resin composition according to claim 1, wherein an epoxy equivalent of the tetramethylbiphenol type epoxy resin ranges from 174 to 300 g/ equivalent.

[Claim 3]

The epoxy resin composition according to claim 1, wherein a melt viscosity at 150°C of the tetramethylbiphenol type epoxy resin ranges from 0.001 to 10 Pa·s.

[Claim 4]

The epoxy resin composition according to claim 1, wherein the tetramethylbiphenol type epoxy resin contains a diglycidyl ether of 4,4'-bishydroxy-3,3',5,5'-tetramethylbiphenyl.

[Claim 5]

A cured product obtained by curing of the epoxy resin composition according to claim 1.

[Claim 6]

A semiconductor sealing material comprising the epoxy resin composition according to claim 1.